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Atty. Dkt. No. 039153-0457 (G1162)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Lopatin et al.

Title: METHOD OF USING TERNARY  
COPPER ALLOY TO OBTAIN A  
LOW RESISTANCE AND LARGE  
GRAIN SIZE INTERCONNECT

Appl. No.: 09/994,395

Filing Date: 11/26/2001

Examiner: Unknown

Art Unit: Unknown

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231, on the date below.	
SANDRA A. MURPHY	(Printed Name)
<i>Sandra A. Murphy</i>	(Signature)
October 22, 2002	(Date of Deposit)

**BEST AVAILABLE COPY**

**REQUEST TO RESCIND PREVIOUS NONPUBLICATION REQUEST**

**35 U.S.C. 122(b)(2)(B)(ii)**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Applicants hereby rescind the previous request that the above-identified application not be published under 35 U.S.C. 122(b).

Respectfully submitted,

Date OCT. 22, 2002

By

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